PRODUCT SPECIFICATION

AMP COMMERCIAL INTERCONNECTION SYSTEM

1. SCOPE

This specification covers the general description and performance requirements of the AMP Commercial Interconnection System (C.I.S.) which includes a complete product line of board-to-board and wire-to-board interconnections.

2. APPLICABLE DOCUMENTS

The latest revision of the following documents form a part of this specification to the extent indicated herein.

2.1. DIN Specifications:

DIN 17660 Wrought copper alloys; copper-zinc alloys (brass); (special brass); chemical composition.

DIN 17662 Wrought copper alloys; copper-tin alloys (tin bronze); chemical composition.

DIN 17670 Plate, sheet and strip of wrought copper and copper alloys; mechanical properties.

2.2. <u>I.E.C. Specifications</u>:

I.E.C. 130, Connectors used for frequencies below 3MHz (Mc/s)

I.E.C. 68, Basic environmental testing procedures for electronic components and electronic equipment.

2.3. <u>E.I.A. Specification</u>:

RS-178-A Solderability test standard.

2.4. Applicable Product Drawings.

SPEC. 108-19011-1 OWNED BY JAPAN IS REFERRING TO THIS DOCUMENT. DO NOT OBSOLETE

				CHK DATE AMP-HOLLAND N.V. S-HERTOGENBOSCH HOLLAND
,,	25/45-2	0.0	6/2	ART (12/11) 24, SATE 106 A NO 108-190.11 N
M	REVISED PAGE 12 RELEASED.	A.B	24/9	SHEET PRODUCT SPECIFICATION AMP- 1 OF 13 COMMERCIAL INTERCONNECTION SYSTEM
LTR	REVISION RECORD	DR	CHK DATE	1 OF 13 COMMERCIAL INTERCONNECTION SYSTEM

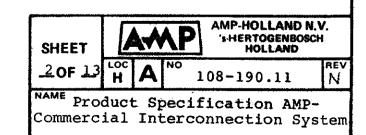
DIST

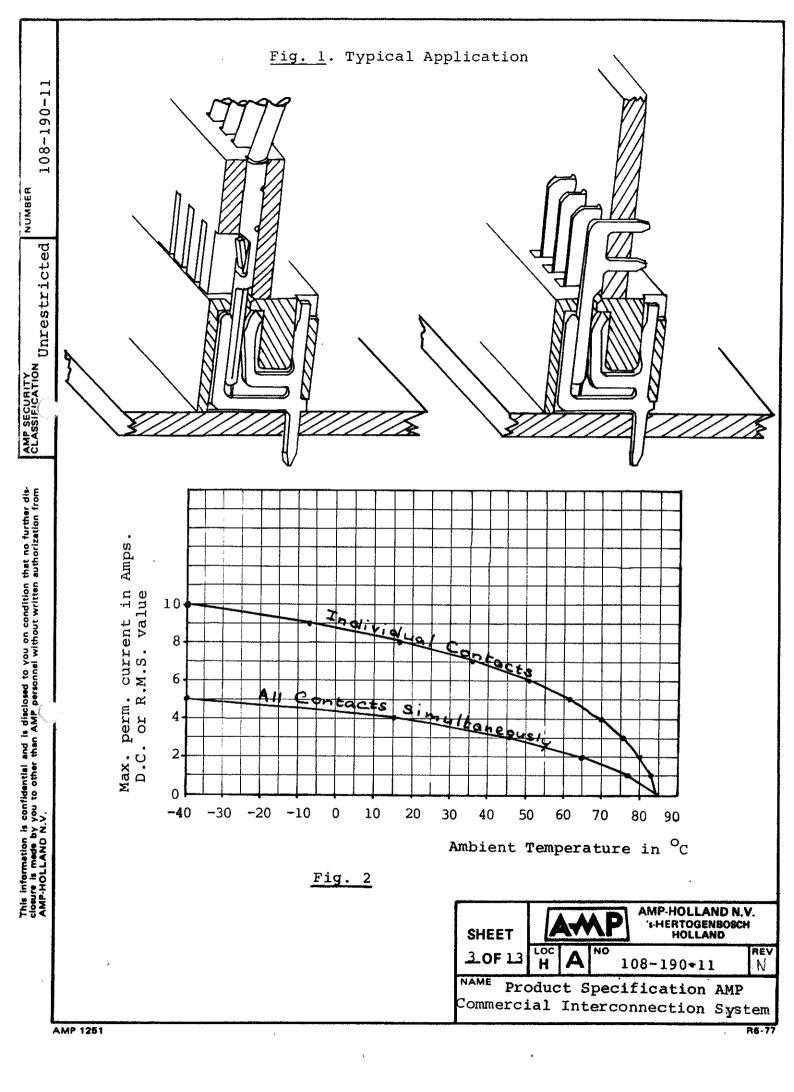
3. PRODUCT DESCRIPTION

- 3.1. Parts The system consists of the following parts:
 - 3.1.1. FEMALE P.C. BOARD CONNECTOR ASSEMBLY, consisting of a housing and a number of receptacles press-fitted in the housing. Female connector assemblies are intended to be soldered to Printed Circuit Boards to accommodate interconnections to printed wiring circuitry.
 - 3.1.2. MALE TABS, Male tabs are intended to be soldered on Printed Circuit Boards.
 - 3.1.3. MALE CONNECTOR ASSEMBLY, consisting of a housing and a number of contacts crimped to appropriate wires and locked in the housing.
- 3.2. Type When Female Connector Assemblies are used in combination with Male Tabs soldered to Printed Circuit Boards, or with Male Connector Assemblies, this System provides adaptability to any center arrangement of 2,5 mm (= .0984 inch) minimum or one multiple of it.

3.3. Design and Construction

- 3.3.1. General Connector Assemblies and Tabs shall be of the design, construction and physical dimensions as specified on the applicable product drawings.
- 3.3.2. Material and Finish -
 - A. Housings The houses are moulded of NORYL Flammability rating 94Vl (SE-1)
 - B. Terminals Terminals shall be fabricated of brass conforming DIN Specifications.
 They shall be timplated with copper underlayer
- 3.4. Application By this system, connections between Printed Circuit Boards and between wire and Printed Circuit Boards, can be made in perpendicular and inline position. Perpendicular connections can be made to both sides of the Printed Circuit Board to which the Female Connector Assemblies are mounted.
 - 3.4.1. Typical Application See fig.1 on page 3 and fig.5 on page 13.





NUMBER

4. PERFORMANCE AND TESTDESCRIPTION

4.1. Temperature rating -

Each assembly shall be capable of continuous operation throughout an ambient temperature range of -40°C to $+85^{\circ}\text{C}$.

4.2. Current rating -

The maximum permissible current shall be as specified in fig. $2 \cdot \mathbf{r}$ on page 3.

4.3. Voltage rating -

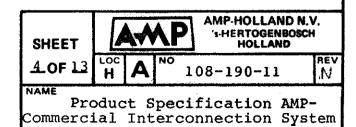
The rated voltage shall be 354 Volts D.C. or A.C. peak as specified in I.E.C. 130-1 clause 5.

4.4. Test Conditions -

Unless specifically stated, tests and examinations required by this specification shall be executed under any combination of conditions as specified in I.E.C. 68-1 clause 5.3.

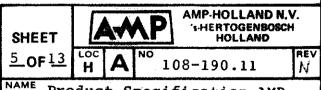
4.5. Test Samples -

The samples submitted for test shall include Female P.C. Board Connector Assemblies whether or not soldered to Printed Circuit Boards. Tabs soldered to Printed Circuit Boards and Male Connector Assemblies with contacts crimped to appropriate wires in Test Groups as mentioned below. The dimensions, plating and mounting shall be as specified on the applicable Product and Customer drawings.



- 4.5.1. TEST GROUP I The samples contained in this group shall consist of Female P.C. Board Connector Assemblies with the required number of Tabs, all soldered to Printed Circuit Boards in one of the arrangements mentioned in Paragraph 3.4. This arrangement depends on application (Reference Figures 3 and 4 for board dimensions)
- 4.5.2. TEST GROUP II The samples contained in this group shall consist of Female and Male Connector Assemblies. The Female P.C. Board Connector Assemblies are soldered to Printed Circuit Boards in one of the arrangements mentioned in Paragraph 3.4. This arrangement depends on application. (Reference Figure 3 for board dimensions).

 Male Connector Assemblies contain Crimp-on Snap-in Contacts crimped to appropriate wires.
- 4.5.3. TEST GROUP III The samples contained in this group shall consist of Female P.C. Board Connector Assemblies not soldered to Printed Circuit Boards.
- 4.5.4. TEST GROUP IV The samples contained in this group shall consist of Male Connector Assemblies with Crimp-on Snap-in Contacts crimped to appropriate wires.
- 4.5.5. TEST GROUP V The samples contained in this group shall consist of Male Tabs not soldered to Printed Circuit Boards.
- 4.5.6. TEST GROUP VI The samples contained in this group shall consist of Crimp-on Snap-in Contacts crimped to appropriate wires.



NAME Product Specification AMP Commercial Interconnection System NUMBER

5. QUALITY ASSURANCE PROVISIONS

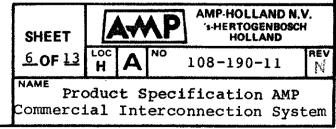
5.1. Qualification Inspection

5.1.1. Sample Selection Connector assemblies and contacts shall be prepared in accordance with applicable Product- and Customer drawings.
They shall be selected at random from current production.
Number of testsamples in accordance with I.E.C. 130-1 clause 9.

- 5.1.2. Test sequence Qualification inspection shall be verified by testing
 the samples to the test sequence as specified under
 6.2.
- 5.1.3. Acceptance When testing the samples as specified, all results
 will fall within the specification limits 99% of the
 time with a confidence level of 95%. Failures attributed to equipment, test set-up or operator deficiencies
 will not disqualify the product. When product failure
 occurs, corrective action will be taken and samples
 shall be re-submitted for qualification.
- 5.1.4. Test Report A report containing test data-analysis and product
 performance evaluation shall be issued at the
 completion of the qualification test program.

5.2. Quality Conformance Inspection

Sampling procedures shall be in accordance with MIL-STD-105. The applicable AMP Quality Inspection Plan will specify the Sampling and Acceptance Quality Level to be used. Dimensional and functional requirements will be in accordance with the applicable Product drawings.



NUMBER

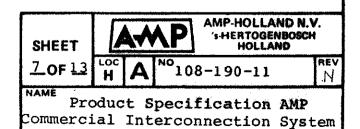
6. TEST SCHEDULE FOR TYPE TESTS

- 6.1. The testschedule, table 1 and 2 on page 8 and 9, shows all tests, conditions of tests as well as the requirements to be met for each type of connector.
- 6.2. The testsequence, table 3 page 10, shows the order in which the tests shall be carried out.
 - 6.2.1. Test Groups and Test Lots -The various Test Groups shall be devided into the following number of Test Lots:

Test Groups I - II and III - 4 Lots each.

Test Group IV - 3 Lots.

Test Groups V - VI - 1 Lot each.



1	TABLE 1						
190-1	Test Description	Clause of I.E.C.130-1	Conditions of test	Requirements			
108-	Examination of Product	11-12		Meets requirements of product drawings			
NUMBER Unrestricted	Termination Resistance	25% of all contacts, with a min. of 2- of each sample shall be measured. The E.M.F. of the measuring circuit shall not exceed 20mV. I = 100mA max. Measuring points see fig.5		10 milliohm max.			
	Insulation Resistance	14.4	100 <u>+</u> 15 V	1000 Megohm min.			
AMP SECURITY	Voltage Proof	14.5	1 minute 1000 V	No breakdown or flashover			
AMP SEC	Damp Heat accelerated	18.2.2	I.E.C. 68-2-4, Test D Not under mechanical and electrical load				
that no further dis- authorization from	Cold	18.2.3	I.E.C. 68-2-1, Test Aa; -40°C Not under mechanical and electrical load				
tion	Damp heat long term.	heat long term. 18.3 I.E.C. 68-2-3, Test C Severity: 21 days half lot mated, half lot unmated. Not under mechand electrical load					
s disclosed to ye	Dry Heat	18.2.1	I.E.C. 68-2-2 Test Ba; + 85 ⁰ C Not under mechanical and electrical load				
confidential and is disclosed to you on condi you to other than AMP personnel without wri V.	Rapid Change of Temperature	18.4	I.E.C. 68-2-14; Test Na, -40°C/+85°C; 6 cycles ½ hour/½ hour Not under mechanical and electrical load				

★ In I.E.C. 130-1 called: Contact Resistance

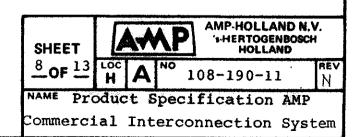


	TABLE 2							
90-11	TEST DESCRIPTION	Clause of I.E.C.130-1	CONDITIONS OF TEST	REQUIREMENTS				
BER 108-1	Salt Mist	18.7	I.E.C. 68-2-11, Test Ka 1 x 24 hours half lot mated half lot unmated					
NUMBER icted	Insertion/Extraction Force	16.1	Measuring force to insert and extract male contacts in female connector assemblies	5 N max./contact 1 N min./contact				
CLASSIFICATION Unrestri	Mechanical Endurance	19.	Number of operations: 25 Frequency of operations 10/minute. Minimum time between successive operations 1 second					
	Vibration	16.4	I.E.C. 68-2-6, Test Fc Procedure B4; 10-55 Hz Displacement 0,75 mm peak. Wires to be used: 0,12 - 0,35 m2 with insulation outer diameter 1,0 - 1,4 mm	No discontinuity above 1 microsecond				
and is disclosed to you on condition that no further dis- than AMP personnel without written authorization from	Contact Retention		Apply an axial load of: 10 N to female contacts 30 N to Crimp-on Snap-in contacts	Contacts will not dislodge from housings				
disclosed to you o	Tensile Strength of Crimp termination	15.4	I.E.C. 68-2-21, Test Ua	20 N min. for 0,12 mm2 wires 70 N min. for 0,35 mm2 wires				
s confidential and is you to other than \$1.V.	Solderability		E.I.A. RS-178-A Solderability Test Standard Test condition 1	5% max. dewetting of functional area				
This information is colorure is made by you AMP-HOLLAND N.V.	Resistance to Soldering Heat	15.3	I.E.C. 68-2-20, Test To Method 1A	No functional damaging				
	AMP 1251		Production	AMP-HOLLAND N.V. 's-HERTOGENBOSCH HOLLAND 108-190-11 Specification AMP erconnection System				

	TABLE 3											
	Test or Examination LOT:		Group I-II			Group III-IV *				V	VI	
			2	3	4	1	2	3	4	1	1	
-11	Examination of Product	X	X	X	Х	X	x	x	X	X	X	
90	Termination Resistance	Х	Х	Х	X	 						
8-1	Insulation Resistance			 		Х	Х	х				
10	Voltage Proof	 		1	 	Х	х	Х			 -	
NUMBER	Insertion/Extraction Force	Х	Х								<u> </u>	
NON	Contact Retention					Х						
ed	Tensile Strength (half lot)										Х	
ict	Damp Heat Long Term			х				Х				
Unrestricted	Change of Temperature				Х						Х	
res	Dry Heat	Х				х						
Un	Tensile Strength (half lot)										Х	
S O O	Damp Heat Accelerated 2 cycl.								Х	Х		
AMP SECURITY	Mechanical Endurance		Х	1								
SSIF	Insertion/Extraction Force		х									
AMP OLA	Damp Heat Accelerated 1 cycl.					х						
\$	Termination Resistance	Х	Х	Х	Х							
a a a a a a	Insulation Resistance				Х	Х						
that no further dis- authorization from	Voltage Proof				Х	Х						
o fu	Salt Mist		Х				Х					
that r	Cold	х				Х						
tion	Damp Heat Accelerated 5 cycl.	х				Х						
t wr	Termination Resistance	х	Х									
ithor	Mechanical Endurance		Х									
o you	Insertion/Extraction Force	Х	Х									
red t	Vibration				X							
MP p	Termination Resistance		Х		Х							
a is	Insulation Resistance					х	Х	х				
ž£	Voltage Proof			ļi		Х	Х	Х				
dentity o oth	Contact Retention					Х			···		Ĺ	
confi /ou t	Solderability					<u> </u>			Х	Х		
2 2 2	Resistance to Soldering Heat								Х			
metio LAN	Examination of Product	Х	Х	х	Х	Х	Х	Х	Х	Х	Х	
This information is confidential and is disclosed to you on condition closure is made by you to other than AMP personnel without written AMP-HOLLAND N.V.	* Note: For Group IV only Lot	1, 2	and	3.							_	
This					ET	A	MF		P-HOLL HERTOG HOLL	ENBOS		
ı					SHEET 1001 - INO				770	IREV		

100F13 H A NO 108-190-11 N

NAME Product Specification AMP

Commercial Interconnection System

